Ben Lancaster

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EXPERIENCE

RTL Design Engineer

ARM Limited

September 2019 – present

- Design and verification of various Systems and NoC IP using SystemVerilog.
- IP requirements capture and specification.
- Programmers-view RTL for memory-mapped peripherals.
- Verification of AMBA protocols and other buses using formal and UVM verification techniques.

Firmware Engineer, Placement

Spirent Communications

June 2016 - August 2017

- Embedded programming on Xilinx MicroBlaze FPGAs and PIC16/24 microcontrollers.
- Implemented on-chip power levelling and calibration for GNSS RF signal generators.
- Controlling on-board fans, LEDs, EEPROM, and other peripherals with I2C and SMBus.
- Configuring, building, and maintaining Embedded Linux distributions using Yocto.
- · Linux USB and PCIe kernel driver development.

EDUCATION

MSc (Eng) Embedded Systems Engineering University of Leeds

2018-2019

- Final Project: Multi-core RISC SoC Design and Implementation for FPGAs.
- Courses include: FPGA Design for System-on-Chip, Digital Signal Processing for Communications, Embedded Microprocessor System Design, Circuits, Medical Electronics and E-Health

BSc (Hons) Computer Science

University of Plymouth

2014 - 2018

- Final Project: FPGA-based 16-bit RISC soft-microprocessor (with IO & interrupts) and Compiler.
- First Class Honours with Certificate of Professional Industrial Experience.
- Awards: Top Final Year Student, Best Final Project, Revell Research Systems Prize
- Courses include: Digital Electronics, Embedded Systems and Compilers, Machine Vision, Computation Theory.

OPEN-SOURCE PROJECTS & CONTRIBUTIONS

- Multi-core RISC System-on-Chip bendl/vmicro16 Up to 96 cores on Spartan-6 and Cyclone V FPGAs.
- 16-bit RISC soft-microprocessor bendl/prco304 An FPGA-based RISC soft-microprocessor written in Verilog, complete with Compiler and programming language.
- ARM Cortex M0 Processor Board bendl/armm0 A 2-layer board for the Minispartan6+ FPGA development kit.
 Features an STM32F0 TSSOP processor, dual power supplies, I2C, ICSP, and LEDs.

ADDITIONAL EXPERIENCE & AWARDS

- Top Final Year Student
- Best Final Project

- Dean's List 2015-2018 member
- · Revell Research Systems Prize

TECHNOLOGIES

- · Digital Design, CMOS, IC Design
- IP Integration
- · Verilog, SystemVerilog
- Cadence, Xilinx/Altera FPGAs, Vivado/ISE, Quartus,
- C, C++, Python, Linux (user + kernel), Bash, Make, CUDA